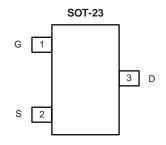


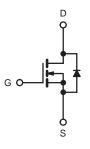
LBSS123LT1G-VB Datasheet N-Channel 100-V (D-S) MOSFET

| PRODUCT SUMMARY | | | | |
|---------------------|-------------------------------|---------------------|--|--|
| V _{DS} (V) | R _{DS(on)} (Ω) | I _D (mA) | | |
| 100 | 2.8 at V _{GS} = 10 V | 260 | | |

FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- Low Threshold: 2 V (typ.)
- Low Input Capacitance: 25 pF
- Fast Switching Speed: 25 ns
- Low Input and Output Leakage
 TrenchFET[®] Power MOSFET
- Compliant to RoHS Directive 2002/95/EC





N-Channel MOSFET

| ABSOLUTE MAXIMUM RATINGS T_{A} = 25 $^{\circ}$ | C, unless otherwise | noted | | | |
|--|-------------------------|----------------------------------|-------------|------|--|
| Parameter | Symbol | Limit | Unit | | |
| Drain-Source Voltage | | V _{DS} | 100 | v | |
| Gate-Source Voltage | | V _{GS} | ± 20 | | |
| Continuous Drain Current (T _{.1} = 150 °C) ^b | T _A = 25 °C | - I _D | 260 | mA | |
| Continuous Drain Current $(T_J = 150 \text{ C})^2$ | T _A = 100 °C | | 150 | | |
| Pulsed Drain Current ^a | | I _{DM} | 800 | | |
| Dense Director of the b | T _A = 25 °C | - P _D | 0.37 | w | |
| Power Dissipation ^b | T _A = 100 °C | | 0.15 | | |
| Maximum Junction-to-Ambient ^b | | R _{thJA} | 350 | °C/W | |
| Operating Junction and Storage Temperature Range | | T _{J,} T _{stg} | - 55 to 150 | °C | |

Notes:

a. Pulse width limited by maximum junction temperature.b. Surface Mounted on FR4 board.

| 5 | 3 | ® VBsemi |
|---|------|-------------|
| W | ww.V | Bsemi.com |

| | | | Limits | | | | |
|---|---------------------|---|---|-------------------|---------|------|--|
| Parameter | Symbol | Test Conditions | Min. | Typ. ^a | Max. | Unit | |
| Static | | • | • | • | • | | |
| Drain-Source Breakdown Voltage | V _{DS} | $V_{GS} = 0 V, I_D = 10 \mu A$ | 100 | | | v | |
| Gate-Threshold Voltage | V _{GS(th)} | $V_{DS} = V_{GS}, I_D = 250 \ \mu A$ | 1 | | 2.5 | v | |
| | | $V_{DS} = 0 V, V_{GS} = \pm 20 V$ | | | ± 10 | | |
| | | $V_{DS} = 0 V, V_{GS} = \pm 15 V$ | | | 1 | 1 µA | |
| Gate-Body Leakage | I _{GSS} | $V_{DS} = 0 V, V_{GS} = \pm 10 V$ | | | ± 150 | nA | |
| | | $V_{DS} = 0 \text{ V}, \text{ V}_{GS} = \pm 10 \text{ V}, \text{ T}_{J} = 85 \text{ °C}$ | $V, V_{GS} = \pm 10 V, T_{J} = 85 \text{ °C}$ | | ± 1000 | | |
| | | $V_{DS} = 0 V, V_{GS} = \pm 5 V$ | | | ± 100 | | |
| Zero Gate Voltage Drain Current | | V _{DS} = 100 V, V _{GS} = 0 V | | | 1 | | |
| | IDSS | $V_{DS} = 100 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 125 \text{ °C}$ | | | 500 | μA | |
| On-State Drain Current ^a | I _{D(on)} | V_{GS} = 10 V, V_{DS} = 7.5 V | 500 | | | | |
| | | $V_{GS} = 4.5 \text{ V}, V_{DS} = 10 \text{ V}$ | 300 | | | mA | |
| Drain-Source On-Resistance ^a | R _{DS(on)} | V _{GS} = 10 V, I _D = 200 mA | | 2.8 | 3 | | |
| | | V _{GS} = 4.5 V, I _D = 150 mA | | 3.0 | | Ω | |
| Forward Transconductance ^a | 9 _{fs} | V _{DS} = 10 V, I _D = 100 mA | 100 | | | mS | |
| Diode Forward Voltage | V _{SD} | I _S = 100 mA, V _{GS} = 0 V | | | 1.3 | V | |
| Dynamic ^a | | | <u> </u> | I | | | |
| Total Gate Charge | Qg | $V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}$ $I_D \cong 150 \text{ mA}$ 0.5 | | 0.5 | | nC | |
| Input Capacitance | C _{iss} | | | 30 | | pF | |
| Output Capacitance | C _{oss} | $V_{\rm DS} = 25 \text{ V}, V_{\rm GS} = 0 \text{ V}$ | | 7 | | | |
| Reverse Transfer Capacitance | C _{rss} | f = 1 MHz | | 2.0 | | | |
| Switching ^{a, b, c} | • | • | <u> </u> | <u> </u> | | | |
| Turn-On Time | t _{d(on)} | $V_{DD} = 30 \text{ V}, \text{ R}_{L} = 150 \Omega$ | | | 20 | | |
| Turn-Off Time | t _{d(off)} | $I_D \cong 200 \text{ mA}, \text{ V}_{\text{GEN}} = 10 \text{ V}, \text{ R}_{\text{G}} = 10 \Omega$ | | 1 | 30 | ns | |

Notes:

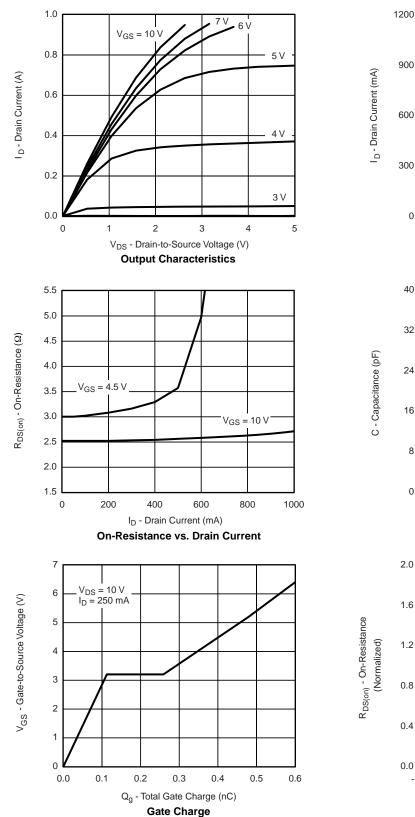
a. For DESIGN AID ONLY, not subject to production testing.

b. Pulse test: PW \leq 300 μs duty cycle \leq 2 %.

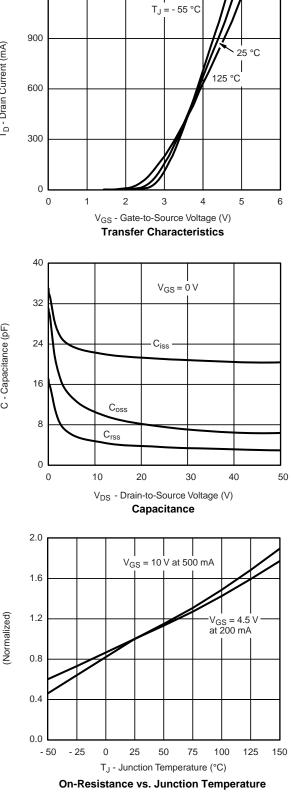
c. Switching time is essentially independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



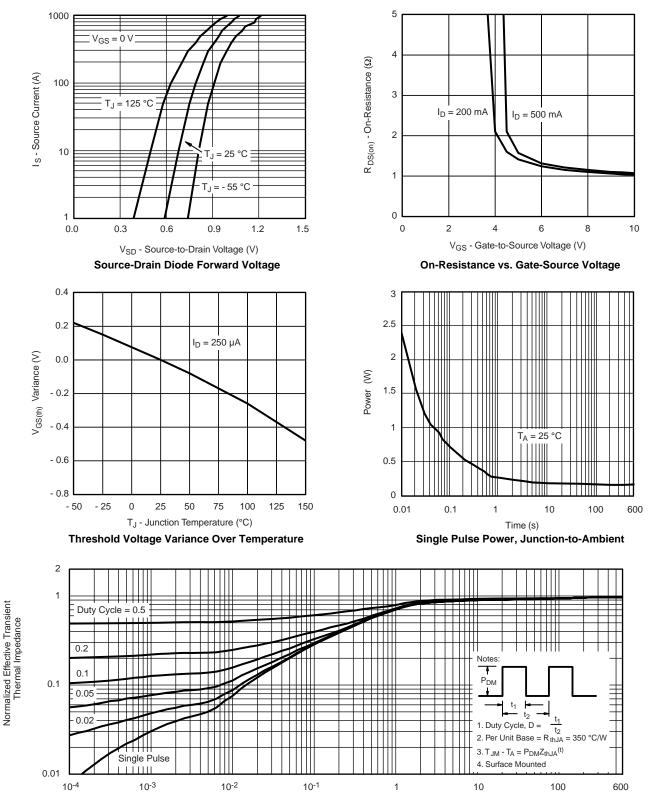


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





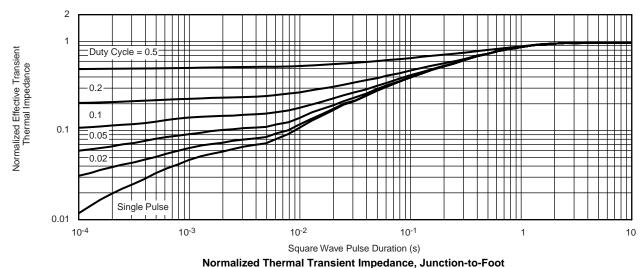
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Square Wave Pulse Duration (s) Normalized Thermal Transient Impedance, Junction-to-Ambient

LBSS123LT1G-VB





THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)

Note

• The characteristics shown in the two graphs

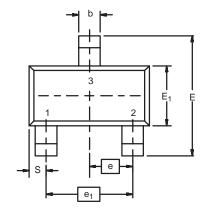
- Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)

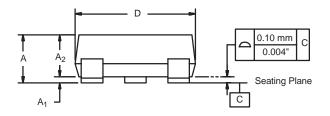
- Normalized Transient Thermal Impedance Junction-to-Foot (25 C)

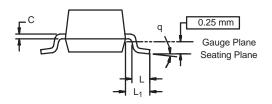
are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.



SOT-23 (TO-236): 3-LEAD



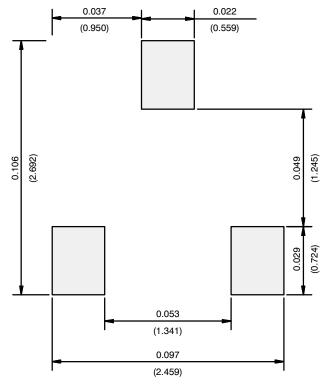




| Dim | MILLIMETERS | | INCHES | | |
|----------------|-------------|------|------------|-------|--|
| | Min | Max | Min | Мах | |
| Α | 0.89 | 1.12 | 0.035 | 0.044 | |
| A ₁ | 0.01 | 0.10 | 0.0004 | 0.004 | |
| A ₂ | 0.88 | 1.02 | 0.0346 | 0.040 | |
| b | 0.35 | 0.50 | 0.014 | 0.020 | |
| C | 0.085 | 0.18 | 0.003 | 0.007 | |
| D | 2.80 | 3.04 | 0.110 | 0.120 | |
| E | 2.10 | 2.64 | 0.083 | 0.104 | |
| E ₁ | 1.20 | 1.40 | 0.047 | 0.055 | |
| е | 0.95 BSC | | 0.0374 Ref | | |
| e ₁ | 1.90 BSC | | 0.0748 Ref | | |
| L | 0.40 | 0.60 | 0.016 | 0.024 | |
| L ₁ | 0.64 Ref | | 0.025 Ref | | |
| S | 0.50 Ref | | 0.020 Ref | | |
| q | 3° | 8° | 3° | 8° | |



RECOMMENDED MINIMUM PADS FOR SOT-23



Recommended Minimum Pads Dimensions in Inches/(mm)

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